International Rectifier

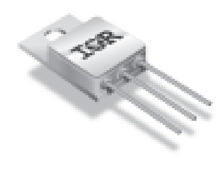
PD-91299E

IRHM9250
JANSR2N7423
200V, P-CHANNEL
REF: MIL-PRF-19500/662
RAD-Hard™ HEXFET® TECHNOLOGY

RADIATION HARDENED POWER MOSFET THRU-HOLE (T0-254AA)

Product Summary

Part Number	Radiation Level	$R_{DS(on)}$	I_D	QPL Part Number
IRHM9250	100K Rads (Si)	0.315Ω	-14A	JANSR2N7423
IRHM93250	300K Rads (Si)	0.315Ω	-14A	JANSF2N7423



TO-254AA

International Rectifier's RAD-Hard HEXFET® technology provides high performance power MOSFETs for space applications. This technology has over a decade of proven performance and reliability in satellite applications. These devices have been characterized for both Total Dose and Single Event Effects (SEE). The combination of low Rds(on) and low gate charge reduces the power losses in switching applications such as DC to DC converters and motor control. These devices retain all of the well established advantages of MOSFETs such as voltage control, fast switching, ease of paralleling and temperature stability of electrical parameters.

Features:

- Single Event Effect (SEE) Hardened
- Low $R_{DS(on)}$
- Low Total Gate Charge
- Proton Tolerant
- Simple Drive Requirements
- Ease of Paralleling
- Hermetically Sealed
- Ceramic Package
- Light Weight
- ESD Rating: Class 2 per MIL-STD-750, Method 1020

Absolute Maximum Ratings

Pre-Irradiation

	Parameter		Units
I_D @ V_{GS} = -12V, T_C = 25°C	Continuous Drain Current	-14	A
I_D @ V_{GS} = -12V, T_C = 100°C	Continuous Drain Current	-9.0	
I_{DM}	Pulsed Drain Current ①	-56	
P_D @ T_C = 25°C	Max. Power Dissipation	150	W
	Linear Derating Factor	1.2	W/°C
V_{GS}	Gate-to-Source Voltage	±20	V
E_{AS}	Single Pulse Avalanche Energy ②	500	mJ
I_{AR}	Avalanche Current ①	-14	A
E_{AR}	Repetitive Avalanche Energy ①	15	mJ
dv/dt	Peak Diode Recovery dv/dt ③	-41	V/ns
T_J T_{STG}	Operating Junction Storage Temperature Range	-55 to 150	°C
	Lead Temperature	300 (0.063 in.(1.6mm) from case for 10s)	
	Weight	9.3 (Typical)	g

For footnotes refer to the last page

Electrical Characteristics @ Tj = 25°C (Unless Otherwise Specified)

	Parameter	Min	Typ	Max	Units	Test Conditions
BV_{DSS}	Drain-to-Source Breakdown Voltage	-200	—	—	V	V_{GS} = 0V, I_D = -1.0mA
$\Delta BV_{DSS}/\Delta T_J$	Temperature Coefficient of Breakdown Voltage	—	-0.24	—	V/°C	Reference to 25°C, I_D = -1.0mA
$R_{DS(on)}$	Static Drain-to-Source On-State Resistance	—	—	0.315	Ω	V_{GS} = -12V, I_D = -9.0A ④
		—	—	0.33		V_{GS} = -12V, I_D = -14A
$V_{GS(th)}$	Gate Threshold Voltage	-2.0	—	-4.0	V	V_{DS} = V_{GS}, I_D = -1.0mA
g_{fs}	Forward Transconductance	4.0	—	—	S	V_{DS} = -15V, I_{DS} = -9.0A ④
I_{DSS}	Zero Gate Voltage Drain Current	—	—	-25	µA	V_{DS}= -160V ,V_{GS} = 0V
		—	—	-250		V_{DS} = -160V, V_{GS} = 0V, T_J = 125°C
I_{GSS}	Gate-to-Source Leakage Forward	—	—	-100	nA	V_{GS} = -20V
I_{GSS}	Gate-to-Source Leakage Reverse	—	—	100		V_{GS} = 20V
Q_g	Total Gate Charge	—	—	200	nC	V_{GS} = -12V, I_D = -14A V_{DS} = -100V
Q_{gs}	Gate-to-Source Charge	—	—	45		
Q_{gd}	Gate-to-Drain ('Miller') Charge	—	—	85		
$t_{d(on)}$	Turn-On Delay Time	—	—	60	ns	V_{DD} = -100V, I_D = -14A V_{GS} = -12V, R_G = 2.35Ω
t_r	Rise Time	—	—	240		
$t_{d(off)}$	Turn-Off Delay Time	—	—	225		
t_f	Fall Time	—	—	220		
$L_S + L_D$	Total Inductance	—	6.8	—	nH	Measured from drain lead (6mm/0.25in. from package) to source lead (6mm/0.25in. from package)
C_{iss}	Input Capacitance	—	4200	—	pF	V_{GS} = 0V, V_{DS} = -25V f = 1.0MHz
C_{oss}	Output Capacitance	—	690	—		
C_{rss}	Reverse Transfer Capacitance	—	160	—		

Source-Drain Diode Ratings and Characteristics

	Parameter	Min	Typ	Max	Units	Test Conditions
I_S	Continuous Source Current (Body Diode)	—	—	-14	A	
I_{SM}	Pulse Source Current (Body Diode) ①	—	—	-56		
V_{SD}	Diode Forward Voltage	—	—	-3.6	V	T_j = 25°C, I_S = -14A, V_{GS} = 0V ④
t_{rr}	Reverse Recovery Time	—	—	775	ns	T_j = 25°C, I_F = -14A, di/dt ≤ -100A/µs
Q_{RR}	Reverse Recovery Charge	—	—	7.2	µC	V_{DD} ≤ -50V ④
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by $L_S + L_D$.				

Thermal Resistance

	Parameter	Min	Typ	Max	Units	Test Conditions
R_{thJC}	Junction-to-Case	—	—	0.83	°C/W	
R_{thJA}	Junction-to-Ambient	—	—	48		Typical socket mount
R_{thCS}	Case-to-Sink	—	0.21	—		

Note: Corresponding Spice and Saber models are available on International Rectifier Web site.

For footnotes refer to the last page

International Rectifier Radiation Hardened MOSFETs are tested to verify their radiation hardness capability. The hardness assurance program at International Rectifier is comprised of two radiation environments. Every manufacturing lot is tested for total ionizing dose (per notes 5 and 6) using the TO-3 package. Both pre- and post-irradiation performance are tested and specified using the same drive circuitry and test conditions in order to provide a direct comparison.

Table 1. Electrical Characteristics @ Tj = 25°C, Post Total Dose Irradiation ⑤⑥

	Parameter	100K Rads(Si)[1]		300K Rads (Si)[2]		Units	Test Conditions
		Min	Max	Min	Max		
BV_{DSS}	Drain-to-Source Breakdown Voltage	-200	—	-200	—	V	V_{GS} = 0V, I_D = -1.0mA
$V_{GS(th)}$	Gate Threshold Voltage	-2.0	-4.0	-2.0	-5.0		V_{GS} = V_{DS}, I_D = -1.0mA
I_{GSS}	Gate-to-Source Leakage Forward	—	-100	—	-100	nA	V_{GS} = -20V
I_{GSS}	Gate-to-Source Leakage Reverse	—	100	—	100		V_{GS} = 20 V
I_{DSS}	Zero Gate Voltage Drain Current	—	-25	—	-25	µA	V_{DS} = -160V, V_{GS} = 0V
$R_{DS(on)}$	Static Drain-to-Source ④ On-State Resistance (TO-3)	—	0.315	—	0.315	Ω	V_{GS} = -12V, I_D = -9.0A
$R_{DS(on)}$	Static Drain-to-Source ④ On-State Resistance (TO-254AA)	—	0.315	—	0.315	Ω	V_{GS} = -12V, I_D = -9.0A
V_{SD}	Diode Forward Voltage ④	—	-3.6	—	-3.6	V	V_{GS} = 0V, I_S = -14A

1. IRHM9250 (JANSR2N7423)
2. IRHM93250 (JANSF2N7423)

International Rectifier radiation hardened MOSFETs have been characterized in heavy ion environment for Single Event Effects (SEE). Single Event Effects characterization is illustrated in Fig. a and Table 2.

Table 2. Typical Single Event Effect Safe Operating Area

Ion	LET MeV/(mg/cm²))	Energy (MeV)	Range (µm)	VDS(V)				
				@VGS=0V	@VGS=5V	@VGS=10V	@VGS=15V	@VGS=20V
Cu	28	285	43	-200	-200	-200	200	—
Br	36.8	305	39	-200	-200	-160	-75	—

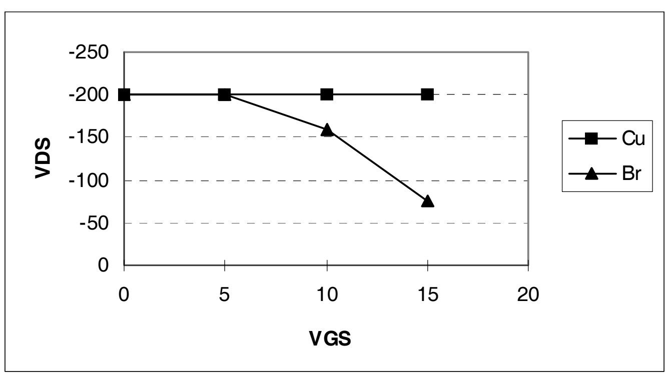


Fig a. Typical Single Event Effect, Safe Operating Area

For footnotes refer to the last page

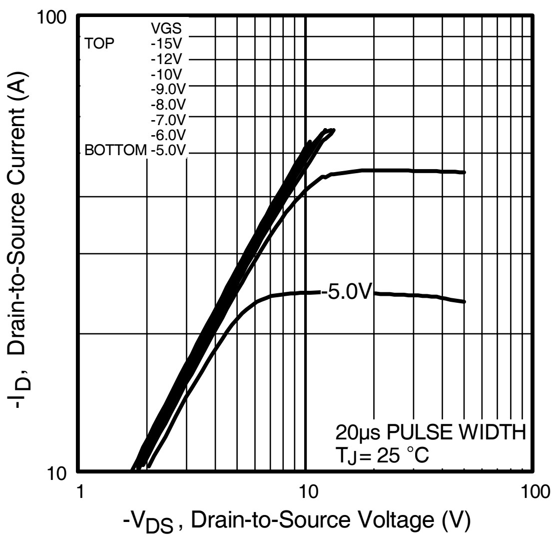


Fig 1. Typical Output Characteristics

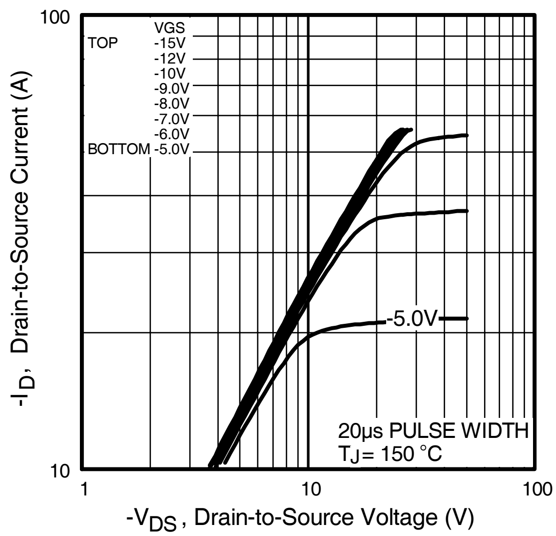


Fig 2. Typical Output Characteristics

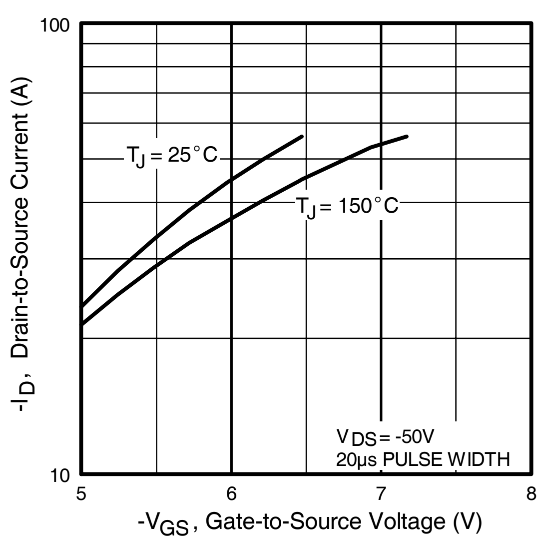


Fig 3. Typical Transfer Characteristics

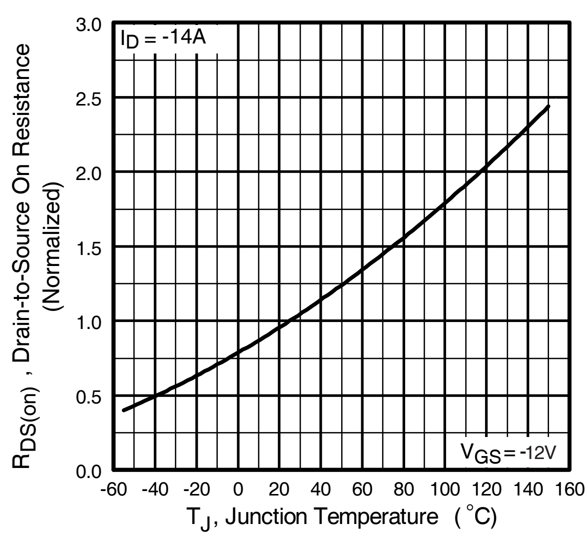


Fig 4. Normalized On-Resistance
Vs. Temperature

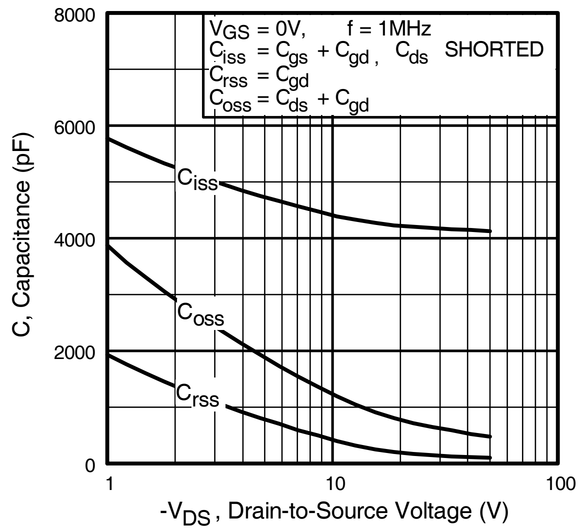


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

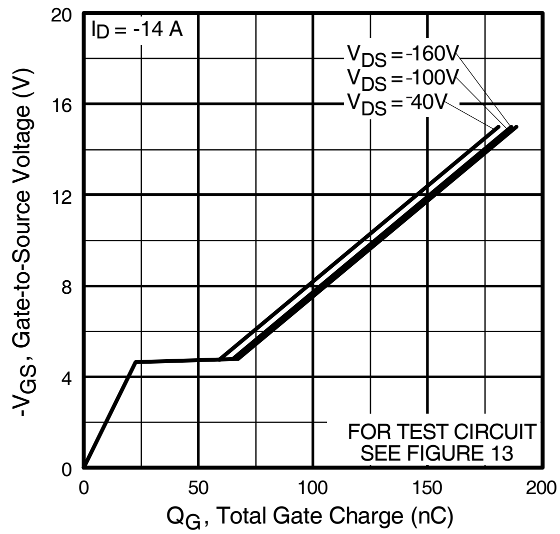


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

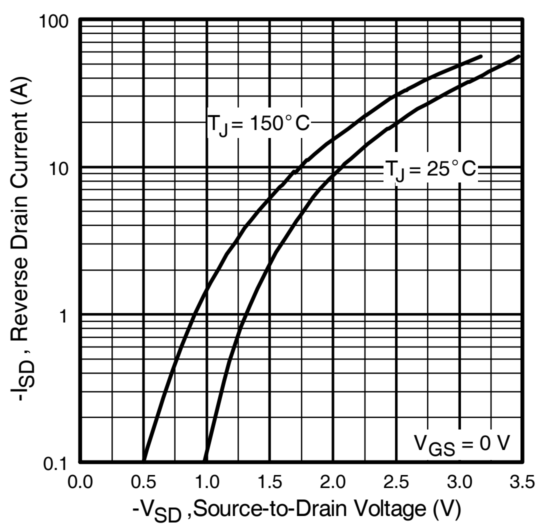


Fig 7. Typical Source-Drain Diode Forward Voltage

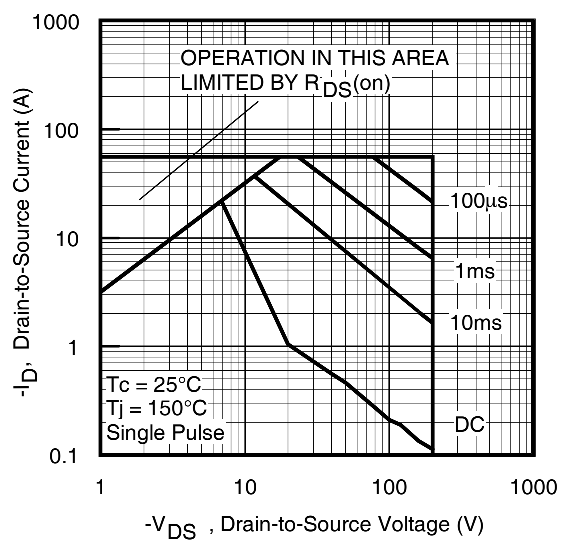


Fig 8. Maximum Safe Operating Area

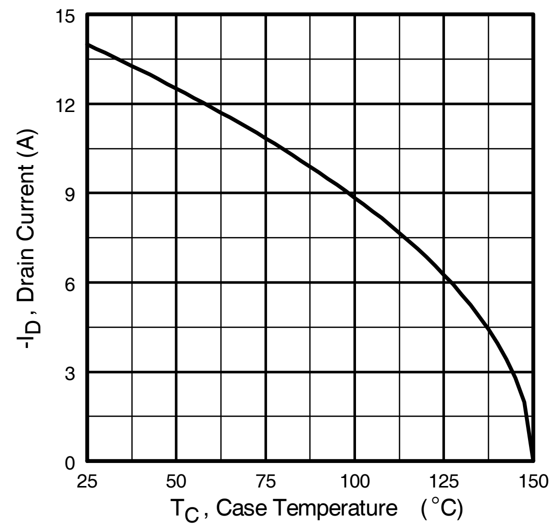


Fig 9. Maximum Drain Current Vs. Case Temperature

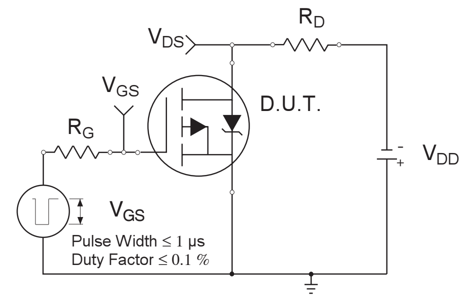


Fig 10a. Switching Time Test Circuit

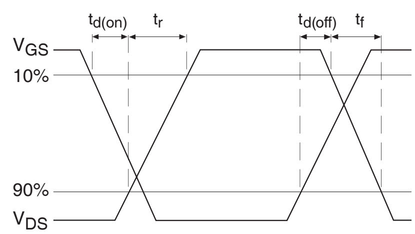


Fig 10b. Switching Time Waveforms

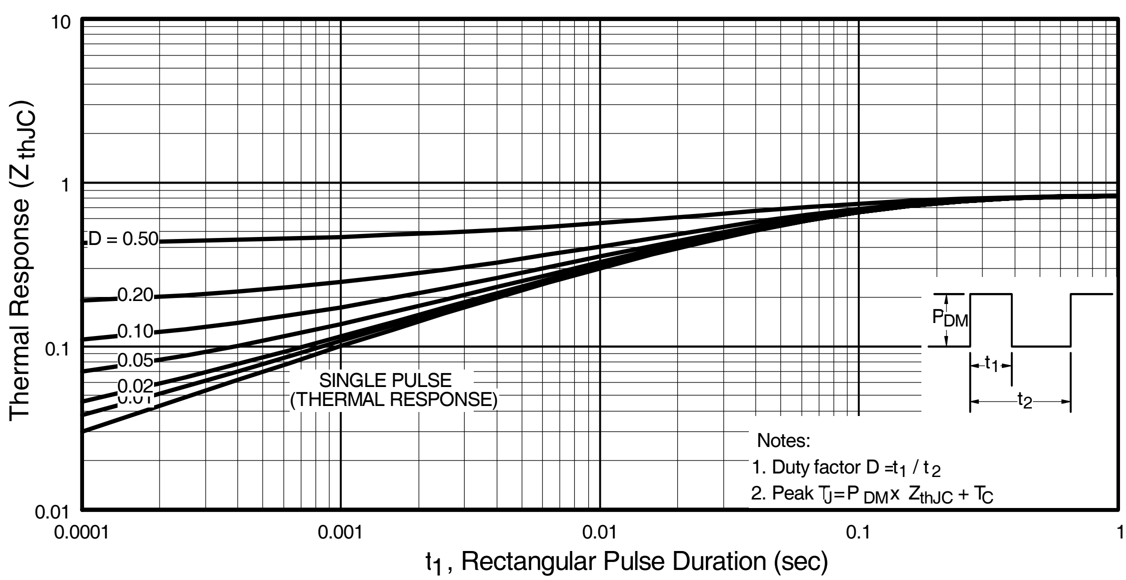


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

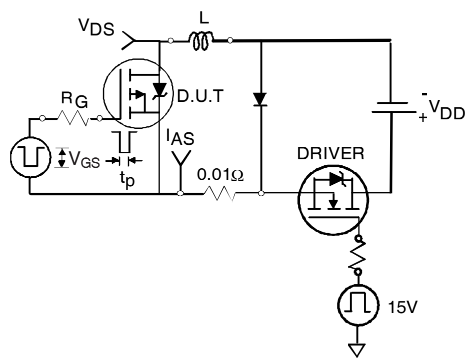


Fig 12a. Unclamped Inductive Test Circuit

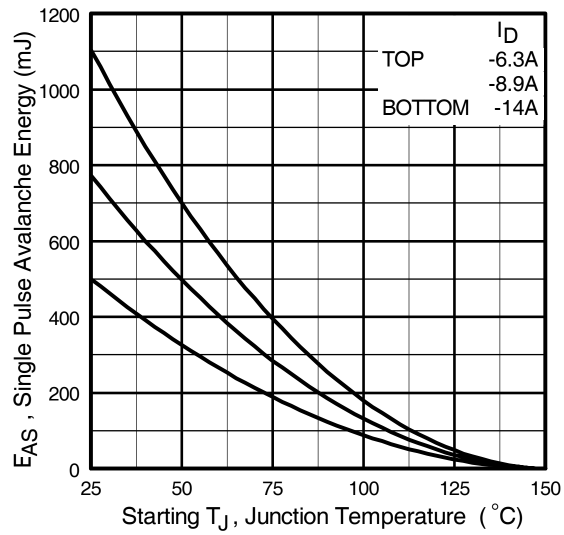


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

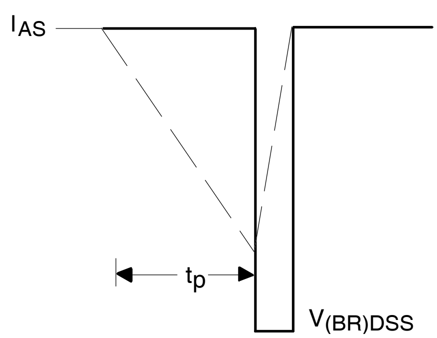


Fig 12b. Unclamped Inductive Waveforms

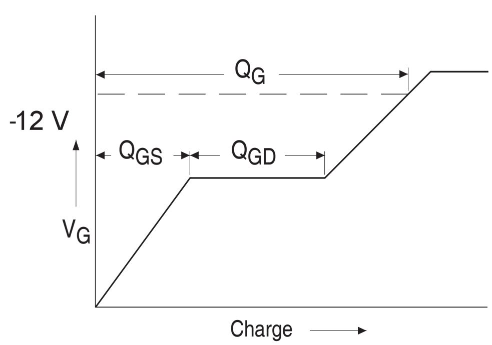


Fig 13a. Basic Gate Charge Waveform

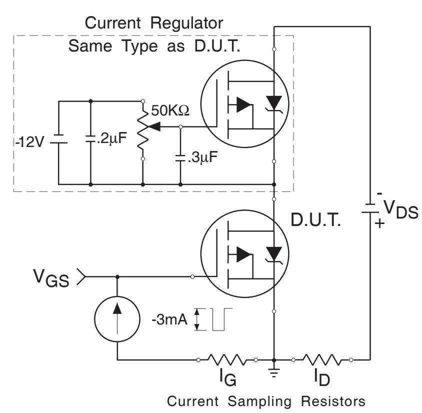


Fig 13b. Gate Charge Test Circuit

Footnotes:

① Repetitive Rating; Pulse width limited by maximum junction temperature.

② V_{DD} = -50V, starting T_J = 25°C, L =5.1mH Peak I_L = -14A, V_{GS} =-12V

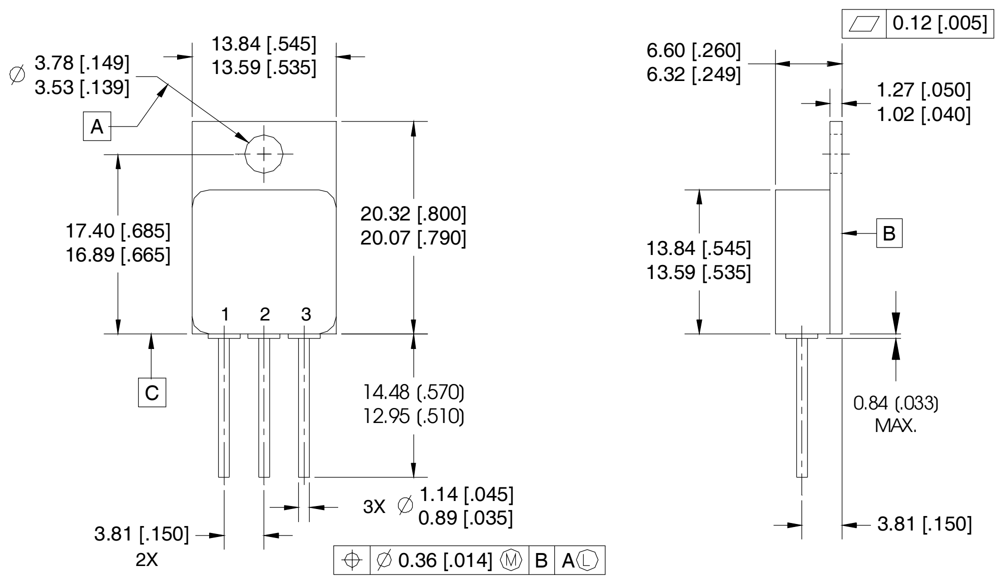
③ I_{SD} ≤ -14A, di/dt ≤ -600A/µs, V_{DD} ≤ -200V, T_J ≤ 150°C

④ Pulse width ≤ 300 µs; Duty Cycle ≤ 2%

⑤ **Total Dose Irradiation with V_{GS} Bias.** -12 volt V_{GS} applied and V_{DS} = 0 during irradiation per MIL-STD-750, method 1019, condition A.

⑥ **Total Dose Irradiation with V_{DS} Bias.** -160 volt V_{DS} applied and V_{GS} = 0 during irradiation per MIL-STD-750, method 1019, condition A.

Case Outline and Dimensions — TO-254AA



NOTES:

1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
3. CONTROLLING DIMENSION: INCH.
4. CONFORMS TO JEDEC OUTLINE TO-254AA.

PIN ASSIGNMENTS

1 = DRAIN
2 = SOURCE
3 = GATE

CAUTION

BERYLLIA WARNING PER MIL-PRF-19500

Package containing beryllia shall not be ground, sandblasted, machined, or have other operations performed on them which will produce beryllia or beryllium dust. Furthermore, beryllium oxide packages shall not be placed in acids that will produce fumes containing beryllium.

International
IOR Rectifier

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